

Tutorial (5/13 Sunday)

3D NAND and Embedded memories

Neuromorphic memories

Invited Speakers (5/14-5/16)

'3D NAND Flash Memory for Data-intensive Applications'

S. Inaba, Toshiba

'Challenges in Automotive Memory Solutions'

H. Wang, NXP

'Ferroelectric HfO₂ and its Impact on the Memory Landscape'

S. Müller, FMC

'Future of DRAM'

G. Sandhu, Micron

'Materials & Processes for Emerging Memory'

M. Pakala, AMAT

'High density 3D Cross-point STT-MRAM'

Y. Huai Avalanche

'Phase-Change Memory: Performance, Roles and Challenges'

G. Navarro, LETI

'Cross point Cu ReRAM with BC doped Selector'

K. Ohba, SONY

'ReRAM technologies for embedded memory and further applications'

S. Ito, Panasonic